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ABSTRACT

2 A method for making UBM (Under Bump Metallurgy) pads and bumps on a wafer
3 is disclosed. Openings are formed in a photoresist layer for forming bumps, a positive
4 liquid photoresist is provided into the openings of the photoresist layer for forming
5 bumps. The positive liquid photoresist is exposed and developed to modify the
6 openings of the photoresist layer. Thus, bumps formed in the modified openings have
7 precise bonding areas on the UBM layer. Using the bumps as a mask, UBM pads under
8 the bumps are formed by etching the UBM layer, so that the reflowed bumps have an
9 uniform height.

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